PCN Number:		20160621000					PCN Date: 06/22/2016			
Title	: Datasheet fo	r DRV8801A	·Q1						•	
Customer Contact:		PCN Manager D					ept: Quality Services			
Char	nge Type:						-		•	
	Assembly Site		Desi	ign			Wafer	Bum	p Site	
	Assembly Process		🛛 Data	Sheet				· Bump Material		
	Assembly Materials		Part number ch		change		Wafer	Bum	Bump Process	
	Mechanical Specification		Test	Test Site			Wafer	r Fab Site		
Packing/Shipping/Labeling		Test	Test Process			Wafer	r Fab Materials			
<u> </u>							Wafer Fab Process			
Notification Details										
Description of Change:										
The product datasheet(s) is updated as seen in the change revision history below:										
SLVSC	79B-JUNE 2014-REVISED JU	JNE 2016							www.ti.com	
Char	nges from Revision A (§	September 2014)	to Revisio	n B					Page	
 Changed the value of T_J from 125°C to 25°C in the test condition (source driver, I_O = -2.8 A, V_{BB} = 8 to 36 V) for the output ON resistance parameter										
Device Family					Change From	m:		Change To:		
DR\	/8801A-Q1			SLVSC79A		SLVSC79B				
	e changes may be //www.ti.com/lit/o				s provided.					
Reas	son for Change:									
To m	nore accurately ref	lect device cl	haracteri	stics.						
Anti	cipated impact o	n Fit, Form	, Functio	on, Quali	ty or Reliat	oilit	y (posi	tive	/ negative):	
	nticipated impact. e actual device.	This is a spe	cificatior	n change a	announceme	nt c	only. The	ere ar	e no changes	
Char	nges to product	identificatio	n result	ting from	this PCN:					
None	2.									
Prod	luct Affected:									
	8801AQRMJRQ1									
	ττ .									

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com